



DISCRIPTION

FEATURES

Molded construction Heat Resistance Molded Resin Excellent Mechanical Strength Excellent Solderability High Reliability Low Profile

OPTIONS

Tape & Reel is Standard (Qty: 2000 Pcs) Bulk Packing Available for smaller quantites Tolerance: J = 5% and K=10% is Standard, tighter Tolerance available (MOQ on request)

APPLICATIONS

VCRs DC/DC Converts Video Cameras CTV, VCR HIC Communication System Automotive Systems LCD/PDP Televisions Hard Disk Drives Network Systems Computer Peripheral Equipment

PHYSICAL CHARACTERISTICS

- Testing : (Equivalents acceptable) Q : .010 μ H to .10 μ H--HP4291A .12 μ H to 100 μ H--HP4285A SRF : .010 μ H to .10 μ H-- HP8720B .12 μ H to 100 μ H--HP4191A RDC : QuadTech 1880 m\Omega
- + Inductance : .010 μH to .10 $\mu H\mathchar`HP4291A$: .12 μH to 100 $\mu H\mathchar`HP4285A$
- Solderability : 90% Terminal coverage Preheat 230°C ± 5°C for 5 ± 5 seconds Flux : Methanol solution with 25% colophony
- IDC : The maximum DC value having L decrease within 10% and Temperature Increase only 20°C with the application of DC bias
- Operating Temperature : -40°C ~ +105°C
- Storage Temperature : -40°C ~ +105°C

ELECTRICAL SPECIFICATIONS

Properties	Test conditions		Value	Unit	Tol.
Inductance		L	5,6	μH	see Site 2
Q factor		Q	25		min.
DC-resistance		DCR typ.		Ω	typ.
DC-resistance		DCR max.	2,50	Ω	max.
Self-Res. Freq.		SRF	36	Mhz	min.
Test-Freq.			7,96	Mhz	
Rated Current		IDC	170	mA	max.
Saturation Current		Isat		mA	typ.

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-Components must be informed before the stage of design-in. Evaluation checks for safety have to be performed on each electronic components used in electrical circuits that require high safety and reliability					Part No.:	S14001-5R6		
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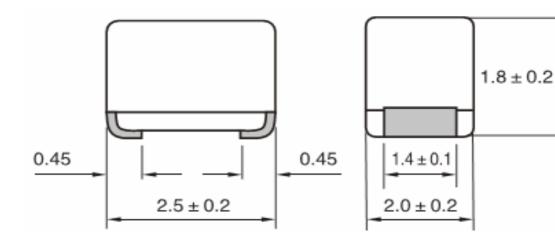
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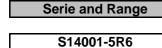


TECHNICAL INFORMATIONS

Dimensions (mm)



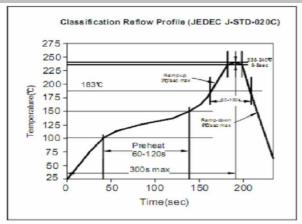
Ordering Information



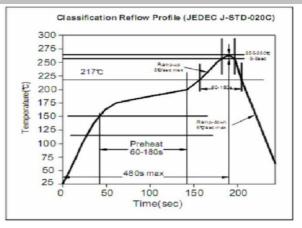
Tolerance	ROHS	Packing			
K	R	TR			
J = 5%	R = ROHS	BU = Bulk Ware			

J = 5%	R = ROHS	BU = Bulk Ware
K = 10%	N = non ROHS	TR = Tape Reel
M = 20%		
N = 30%		

Soldering Profile for Lead Free Soldering 235-240°C



Soldering Profile for Lead Free Soldering 255-260°C



 This electronic component is meant to be used in general electronic equipment. Before the incorporation of this component into any equipment with higher and more reliable requirements such as aviation, aerospace, submarine, nuclear control, transportation, transportation signal, disaster prevention, medical, public information network, etc. or if there is a possibility of injuries or damages to the human body, Edcon 					SMT WOUND MOLDED CHIP INDUCTORS			
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